2SC5845

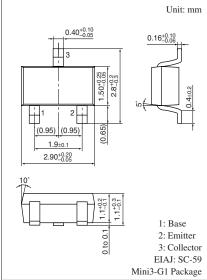
Silicon NPN epitaxial planar type

For general amplification

Features

- High forward current transfer ratio hFE
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

ing	packing a	nd the magaz	ine pack-
Absolute Maximum Rating	$s T_a = 2$	5°C	
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	60	V
Collector-emitter voltage (Base open)	V _{CEO}	50	V
Emitter-base voltage (Collector open)	V _{EBO}	7	V
Collector current	I _C	100	mA
Peak collector current	I _{CP}	200	mA
Collector power dissipation	P _C	200	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Ab

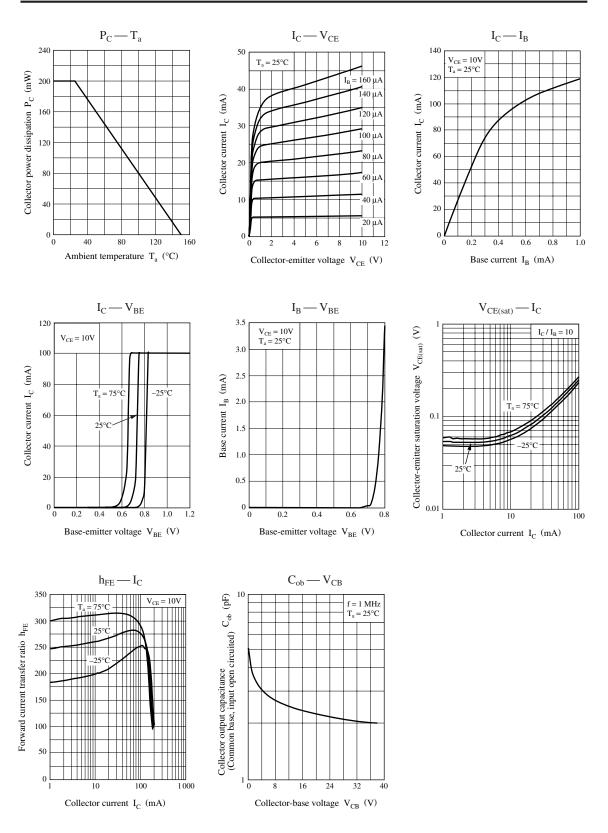
Marking Symbol: 7M

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, \ I_{\rm E} = 0$	60			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 2 {\rm mA}, I_{\rm B} = 0$	50			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$	7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 20 V, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 10 \text{ V}, I_B = 0$			100	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, \text{ I}_{C} = 2 \text{ mA}$	160		460	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 100 \text{ mA}, I_{\rm B} = 10 \text{ mA}$		0.1	0.3	V
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2.2		pF
(Common base, input open circuited)						
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		100		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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